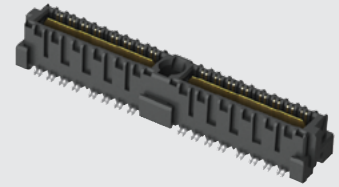


QMS-026-06.75-L-D-A



(0.635 mm) .025"

QMS SERIES

RUGGED GROUND PLANE HEADER

SPECIFICATIONS

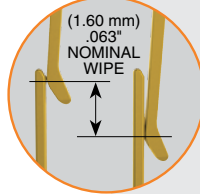
For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material:
Liquid Crystal Polymer
Terminal & Ground Plane Material:
Phosphor Bronze
Plating:
Au over 50 μm (1.27 μm) Ni (Tin on Ground Plane Tail)
Current Rating:
Contact:
2.6 A per pin
(1 pin powered per row)
Ground Plane:
15.7 A per ground plane
(1 ground plane powered)
Operating Temp:
-55 °C to +125 °C
Voltage Rating:
300 VAC mated with QFS
RoHS Compliant:
Yes

Board Mates:
QFS

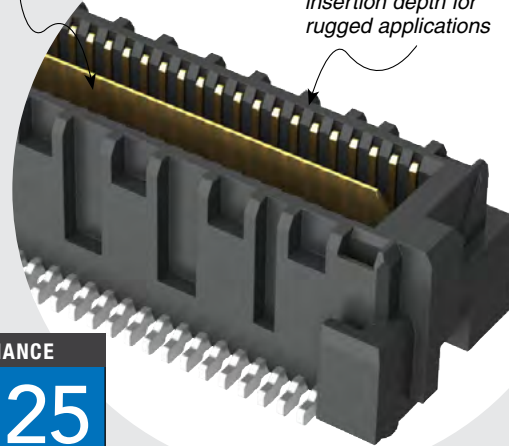
Cable Mates:
6QCD

Standoffs:
SO, JSOM



Integral metal plane for power or ground

Increased insertion depth for rugged applications



HIGH-SPEED CHANNEL PERFORMANCE

QMS-DP/QFS-DP @ 10 mm Mated Stack Height
Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com or contact SIG@samtec.com

25 Gbps

ALSO AVAILABLE (MOQ Required)

- Other platings
 - Guide Posts
 - Without PCB Alignment Pins (05.75 and 06.75 only)
 - Hot Pluggable
 - 64 (-DP) and 104 positions per row
- Contact Samtec.

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (026-052)
(0.15 mm) .006" max (078)
Board Stacking:
For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



STANDARDS

- SUMIT™
- PCI/104-Express™

PROTOCOLS

- 100 GbE
- Fibre Channel
- XAUI
- PCI Express®
- SATA

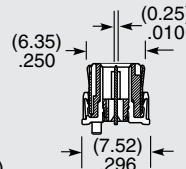
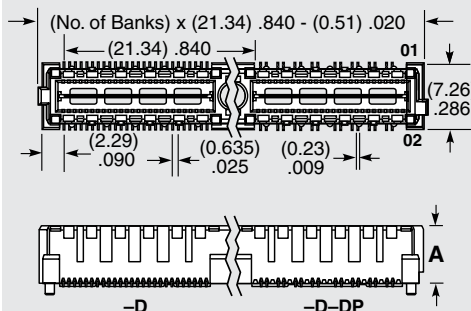
Note: Some lengths, styles and options are non-standard, non-returnable.

QMS	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	-026, -052, -078 (52 total pins per bank = -D)	-016, -032, -048 (16 pairs per bank = -D-DP) (-078 & -048 Not available with -09.75 lead style)	-L (-05.75 and -06.75 lead style only) = 10 μm (0.25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)	-D = Single-Ended -D-DP = Differential Pair		-K = (5.50 mm) .217" DIA Polyimide film Pick & Place Pad

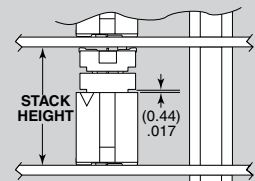
Specify LEAD STYLE from chart

LEAD STYLE	A	MATED HEIGHT*	
		QFS LEAD STYLE -04.25	-06.25
-05.75	(5.38) .212	10 mm	12 mm
-06.75	(6.35) .250	11 mm	13 mm
-09.75	(9.35) .368	14 mm	16 mm

*Processing conditions will affect mated height. See SO Series for board space tolerances.



APPLICATION



Requires Standoff
SO-1524-03-01-01-L or JSOM-1524-02 for 15.24 mm or SO-2215-02-01-01-L for 22 mm board spacing. Connectors designed to not fully seat when mated.

INDUSTRY STANDARD	INTERCONNECTS			
	TERMINAL	SOCKET	BANKS	STACK HEIGHT
SUMIT™	ASP-129637-01	ASP-129646-01	1	15.24 mm
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15.24 mm
PCI/104-Express™	ASP-129637-13	ASP-129646-22	1	15.24 mm
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm